



Date: Sept. 9, 2003

TO: Examiner Julio J. Maldonado (703) 872-9319
Art Unit: 2823

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Subject Matter: 09/ 885,784 Attorney Doc: 67,200-327

Message:

Total number of pages sent: - 12 - (including this cover sheet)

67,200-327; TSMC 00-132
Serial Number 09/885,784

OFFICIAL

RESPONSE TO OFFICE ACTION MADE FINAL

TO: Commissioner for Patents
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FROM: Tung & Associates
838 West Long Lake Road - Suite 120
Bloomfield Hills, MI 48302

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DATE: 3 September 2003

REF: APPLICANT : Liang
SERIAL NO. : 09/885,784
ART UNIT : 2823
FILING DATE : 20 June 2001
ATTY NO. : 67,200-327; TSMC 00-132
EXAMINER : Julio J. Maldonado
TITLE : Laminating Method for Forming Integrated Circuit
Microelectronic Fabrication

Sir:

In response to an office action mailed on 8 July 2003 and made FINAL, please consider the following remarks pertaining to the above referenced application.

There are no amendments to the specification, claims or drawings. A Listing of the Claims begins on page 2 of this paper. Remarks begin on page 5 of this paper.

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office at facsimile number 703-872-9319, on Sept. 9 2003.



Kathy Dixon